

TF E2771F

ELECTRICALLY CONDUCTIVE FILM

TECHNICAL DATA

June, 2010

Product Description

TechFilm E2771F3 is a three thousands of an inch film that typicall comes supported with two thousands of an inch carbon non-woven mesh. It is a high performance electrically conductive B-staged film adhesive specially formulated for bonding to gold, brass and copper substrates.

APPLICATIONS

- EMI/RF Shielding
- Ground Planes

FEATURES

- Electrically conductive
- B-staged film
- Chemical, heat, moisture resistant

RECOMMENDED SUBSTRATES

- Gold
- Aluminum
- Copper

CURED PROPERTIES*

Property	Value	Test Method
Color	Dark Grey	Visual
Specific Gravity	1.3	ASTM D792
Glass Transition Temperature, C	114	ASTM E1545
Lap Shear Strength, 25C, psi	to Aluminum: 2900	ASTM D1002
	to Gold: 1900	ASTM D1002
	to Copper: 2950	ASTM D1002
Volume Resistivity, 25C, Ohm-cm	2	TFTEST004A

CURE SCHEDULE*

Property	Value	Test Method
Cure Time @ 150°C, min	30	Typical Cure Schedule
Cure Time @ 165°C, min	15	Alternate Cure Schedule
Cure Time @ 110°C, min	120	Alternate Cure Schedule

Storage: Store in dry conditions, out of sunlight and in tightly sealed containers.

Shelf Life: Two days @ 20°C One month @ 10°C Three months @ -10°C One year @ -40°C

Revision Number: 1-New Date: 01 June, 2010

Resin Designs, LLC 11 State Street Woburn, MA 01801 www.resindesigns.com P 781-935-3133 F 781-935-3144

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